

Patent

Customer No.: 3156  
Docket No.: 10663-US-PA  
Application No.: 10/605,305  
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**APR 27 2005**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of  
Applicant : Ho et al.  
Application No. : 10/605,305  
Filed : 2003/09/22  
For : BUMP PROCESS FOR FLIP CHIP PACKAGE  
Art Unit : 2829  
Examiner : GEYER, SCOTT B

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**REQUEST FOR CORRECTION TO PUBLICATION OF APPLICATION**  
**VIA FACSIMILE ONLY (002-1-703-308-5065)**

U.S. Patent and Trademark Office  
Office of Public Records,  
Alexandria, VA 22313-1450

Dear Sir/Madam,

We are writing in relation to the Notice of Publication of Application of the above-identified application.

After a review of the publication of the subject application, it is noticed that apart from the first page of the publication, the rest of the publication of the application is incorrect and verified to be that of U.S. Patent No. 09/844,224, filed on April 27, 2001.

We respectfully request the U.S. Patent and Trademark Office to replace the incorrect publication with the one we previously submitted soon.

Thank you so much for your attention. Please do not hesitate to contact us if you have any questions regarding this matter.

Respectfully Submitted,  
JIANQ CHYUN Intellectual Property Office

Date: April 27, 2005

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